



# BRUS1 BRUS5

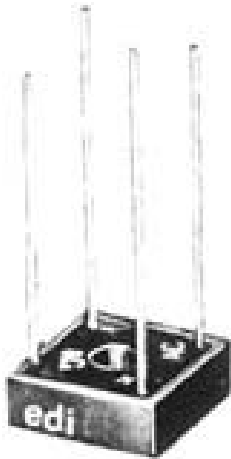
## MINIBRIDGE<sup>®</sup>

50 ns. ULTRA-FAST RECOVERY

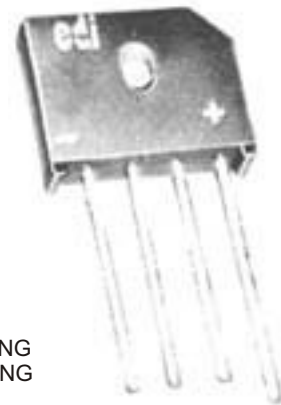
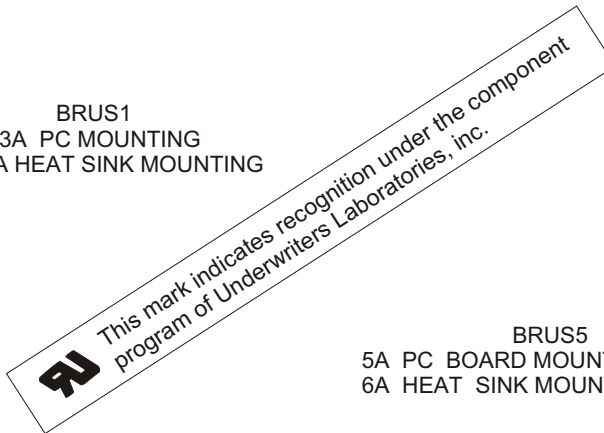
4 to 6 AMPERES

SINGLE-PHASE, FULL-WAVE BRIDGES

HEAT SINK • CHASSIS • PC BOARD MOUNTING



BRUS1  
3A PC MOUNTING  
4A HEAT SINK MOUNTING



BRUS5  
5A PC BOARD MOUNTING  
6A HEAT SINK MOUNTING

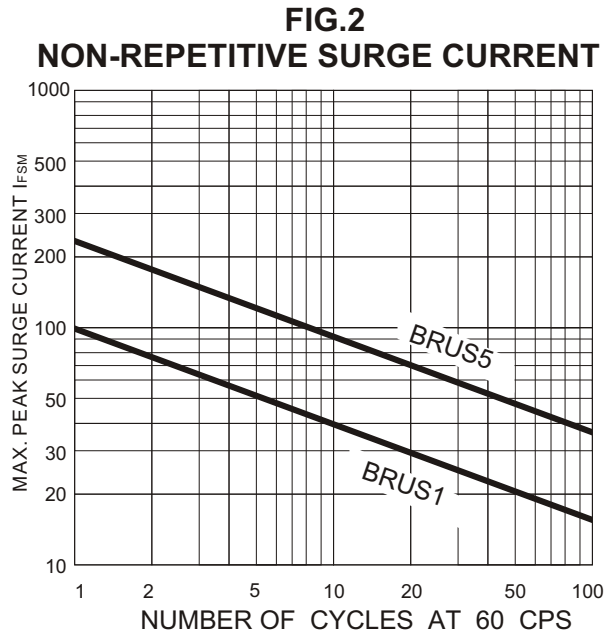
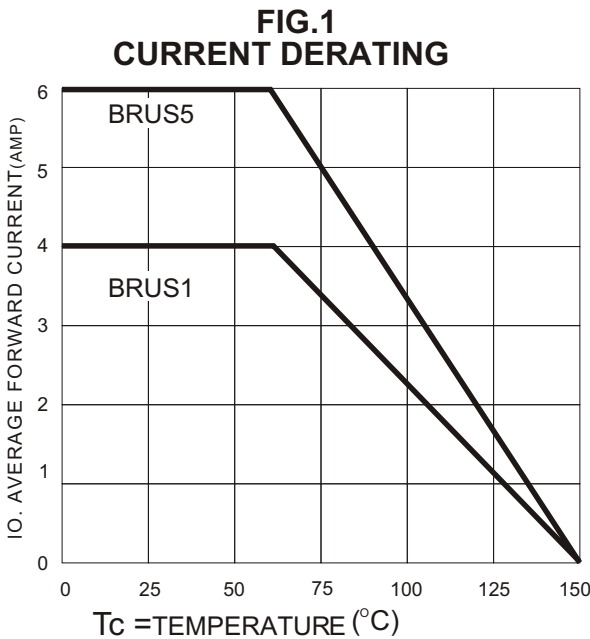
PRV/LEG	50V	100V	200V	400V	500V	600V
BRUS1 SERIES	BRUS105	BRUS110	BRUS120	BRUS140	BRUS150	BRUS160
BRUS5 SERIES	BRUS505	BRUS510	BRUS520	BRUS540	BRUS550	BRUS560

ELECTRICAL CHARACTERISTICS PER LEG (at T <sub>A</sub> =25 °C Unless Otherwise Specified)	SERIES DESIGNATION		UNITS
	BRUS1	BRUS5	
Average Output Current, I <sub>o</sub> @ 60 °C T <sub>C</sub> (Fig.1)	4	6	Amps
Average Output Current, I <sub>o</sub> @ 80 °C T <sub>L</sub> (Fig.2)	3	5	Amps
Max. Forward Voltage Drop, I <sub>F</sub> <small>BRUS1 Series = 2A BRUS5 Series = 4A</small>	1.3	1.3	Volts
Max.DC Reverse Current @ PRV and 25 °C, I <sub>R</sub>	10	10	μA
Max.DC Reverse Current @ PRV and 100°C, I <sub>R</sub>	200	200	μA
Max.Reverse Recovery Time, T <sub>rr</sub> (Fig.3)	50	50	Nanosec.
Max.Peak Surge Current, I <sub>FSM</sub> (8.3ms) (Fig.2)	100	240	Amps
Storage Temperature Range, T <sub>STG</sub>	-55 to+150		°C
Ambient Operating Temperature Range, T <sub>A</sub>	-55 to+150		°C
Thermal Resistance (Total Bridge), R <sub>θj-c</sub>	7.7 typ.	8.7 typ.	°C/W

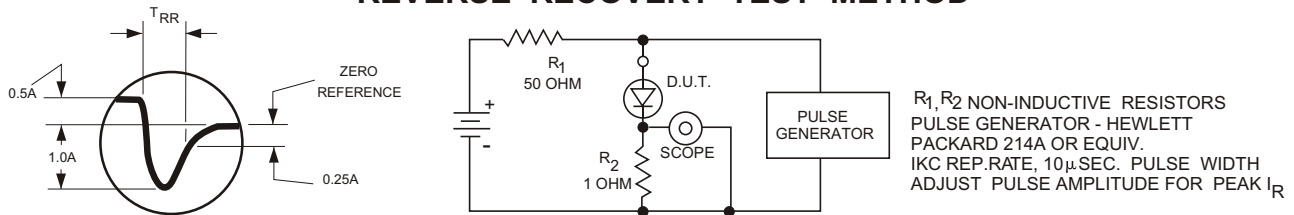
NOTE: A thin film of silicone thermal compound is recommended between the Minibridge<sup>®</sup> case and mounting surface for improved thermal conduction.

EDI reserves the right to change these specifications at any time without notice.

# BRUS1 BRUS5

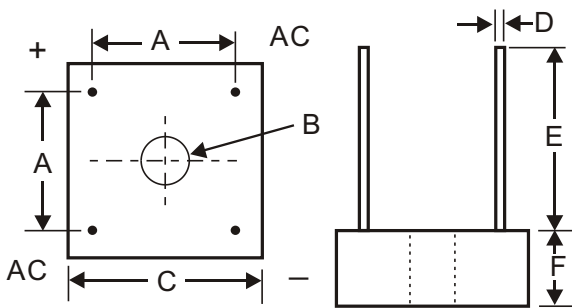


**FIG.3 REVERSE RECOVERY TEST METHOD**



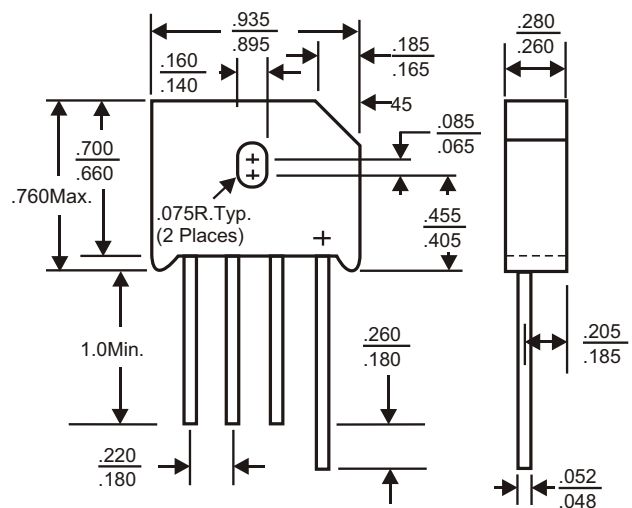
**BRUS MECHANICAL OUTLINE**

Dielectric test voltage 2,500 V rms., max. 50-60Hz



LTR	INCHES	MILLIMETERS
A	.411-.441	10.44-11.20
B	.137-.167DIA	3.48-4.24DIA
C	.590-.610	14.99-15.49
D	.038-.042	.97-1.07
E	.750MIN	19.05MIN
F	.300MAX	7.62MAX

**BRUS5 MECHANICAL OUTLINE**



Maximum lead and terminal temperature for soldering, 3/8 inch from case, 5 seconds at 250 °C.

A thin film of silicone thermal compound is recommended between the Minibridge® case and mounting surface for improved thermal conduction.

**ELECTRONIC DEVICES, INC.** DESIGNERS AND MANUFACTURERS OF SOLID STATE DEVICES SINCE 1951.

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